

SOLDER AREA
 KEEP OUT AREA

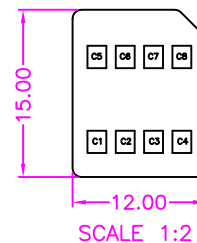
MATERIALS

HOUSING: HI-TEMP. PLASTIC (UL 94V-0), BLACK
 SHELL: STAINLESS STEEL, NICKEL PLATING
 SOLDER PAD: STAINLESS STEEL, GOLD PLATING
 TERMINAL: COPPER ALLOY, GOLD PLATED

SPECIFICATION

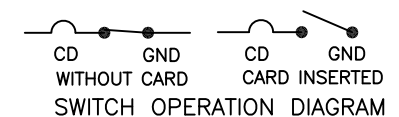
CURRENT RATING: 1.0 AMP MAX
 DIELECTRIC WITHSTANDING: 500V AC FOR ONE MINUTE
 CONTACT RESISTANCE: 100m OHMS MAX
 INSULATION RESISTANCE: 1000M OHMS MIN AT DC 500V
 OPERATION TEMPERATURE: -40°C~+85°C

MICRO SIM CARD



MicroSIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

ELECTRIC FUNCTION	DETECT SWITCH
WITHOUT CARD	CLOSED
CARD INSERTED	OPEN



RoHS Compliant

TOLERANCES ARE



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DRAWING BY CY

CHECKED BY GENIUS

UNIT / mm SCALE 1 : 1

DATE

SIZE A4

X ± 0.40
 .X ± 0.30
 .XX ± 0.20
 .XXX ± 0.10
 ANG ±

PJECTION

照片框

ORDER INFORMATION

MISCP-W16E15A-06-LF

SERIES

LEADFREE
 06 WAY
 SWITCH CLOSED
 HIGH 1.5mm
 PAD TO PAD 16mm
 90°SMT

DESCRIPTION: MICRO SIM CARD, 9PIN, PCB MOUNT, SMT, METAL SHIELD, PUSH PUSH TYPE H=1.50mm, FEMALE